Substitute fo	or form 1449A/PTO		-	Complete if Known		
			CUDE	Application Number	10/799,204	
INFUR	RMATION I	DISCEC	JOURE	Filing Date	03/11/2004	
STATI	EMENT BY	APPLI	CANT	First Named Inventor	Joan K. Vrtis	
	use as many sheet			Art Unit	2835 3729	
(use as many sheets as necessary)				Examiner Name	Tolin, Gerald P.	
Sheet	1	of	3	Attorney Docket Number	42P13111D	

			U.S. PATE	NT DOCUMENTS	
Examiner Initials*	Cite No.'	Document Number  Number - Kind Code <sup>2</sup> (if known)	Publication Date Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TN		US-2002/0009826 A1	01-24-2002	Chien	
		US-2002/0171132 A1	11-21-2002	Buchwalter et al.	
		US-4,858,073	08-15-1989	Gregory	
		US-5,489,805	02-06-1996	Hackitt et al.	
		US-6,008,988	12-28-1999	Palmer	
		US-6,197,859 B1	03-06-2001	Green et al.	·
1/		US-6,219,243 B1	04-17-2001	Ma et al.	
-		US-6,228,452 B1	05-08-2001	Oka et al.	
TN		US-6,462,410 B1	10-08-2002	Novotny et al.	
		US-			

FOREIGN PATENT DOCUMENTS								
Examiner	Cite	Foreign Patent Document			Pages, Columns, Lines,			
Initials*	No.'	Country Code* - Number* - Kind Code* (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear			
		×						
	ı	200 700 700						

	Examiner	/Tai Nguyen/	Date	09/15/2006
ı	Signature	, 202 1190,000	Considered	1

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

'Applicant's unique citation designation number (optional). 'See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. 'Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 'For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. 'Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 18 if possible. 'Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08A (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wtr) 08/11/2003.

Substitute fo	or form 1449A/PTO			Complete if Known		
			CLIDE	Application Number	10/799,204	
INFOR	RMATION I	JIOCTO:	<b>SUKE</b>	Filing Date	03/11/2004	
STATEMENT BY APPLICANT			CANT	First Named Inventor	Joan K. Vrtis	
<b>-</b>			<b></b>	Art Unit	Joan K. Vrtis 2835 3729	
		<del></del>		Examiner Name	Tolin, Gerald P.	
Sheet	2	of	3	Attorney Docket Number	42P13111D	

Examiner Initials* Cite No.1		Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or						
		country where published.						
		BATH, J., Selectron Corp., Lead Free Process Group Update, National Electronics Manufacturing Initiative, Jan. 17, 2001.						
	·	DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Enthone-OMI Inc., Conference Proceedings; Surface Mount International Conference, September 10, 1996, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.						
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Proceedings Of the SMTA, 1996, Enthone-OMI Inc., New Haven, Connecticut, pages 763-776.						
	<del></del>	HART, K., ET AL., DFE Study Gives Alternative Finishes the Green Light, PC FAb, Oct. 2000.						
-		JOHNSON, R.W., ET AL, Thermal Cycle Reliability of Solder Joints to Alternate Plating Finishes, paper from Auburn University, 2000.						
		MORAWSKA, Z, ET AL., Lead-Free Solderability Preservative Coatings for PCBs, Advanced Microelectronics, v. 28, no. 3, May/June 2001.						
TN		PARQUET, D., ET AL., OSP: The High Performance Surface Finish, Electronic Interconnect Conference, 1997.	+					

Examiner	/Tai Nguyen/	Date	09/15/2006
Signature	, 545 11, 545	Considered	03/13/2000

<sup>\*</sup>Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

<sup>&#</sup>x27;Applicant's unique citation designation number, 'Applicant is to place a check mark here if English language Translation is attached.

Substitute t	for form 1449A/PTO	1		Complete if Known		
			CHBE	Application Number	10/799,204	
INFUI	RMATION I	DISCL	JOUKE	Filing Date	03/11/2004	
STATEMENT BY APPLICANT				First Named Inventor	Joan K. Vrtis	
• • • • • • • • • • • • • • • • • • • •				Art Unit	2835 3729	
			Τ	Examiner Name	Tolin, Gerald P.	
Sheet	3	of	3	Attorney Docket Number	42P13111D	

		NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	Ţ²
TN		ROMM, D., ET AL., Evaluation of Ni/Pd-Finished ICs with Lead Free Solder Alloys, Texas Instruments Application Report SZZA024, Jan. 2001.	
		SOLBERG, V., Impact of PCB Surface Finish on SMT Assembly Process Yield, Application Note from Tessera Corp.	
		SYED, A., Amkor Technology Corp., Surface Mount Requirements for Advanced Packaging Solutions, 2000.	
		WENGENROTH, KARL, ET AL., OSPS: Addressing Future Surface Finishing Needs, Enthone-OMI, Conference Proceedings, Surface Finishes Forum Conference, May 4, 2000, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.	
		Double Sided 4Mb SRAM Coupled Cap PBGA Card Assembly Guide, IBM Application Note, Feb. 1998.	
TN		Kester Solder Paste for Surface Mount and General Electronics Assemblies, Online Catalog of Preferred Products, 2001.	
,			

/Tai Nguyen/	Date Considered	09/15/2006
	/Tai Nguyen/	/Tai Nguyen/ Date Considered

<sup>\*</sup>Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

<sup>&#</sup>x27;Applicant's unique citation designation number. 'Applicant is to place a check mark here if English language Translation is attached.